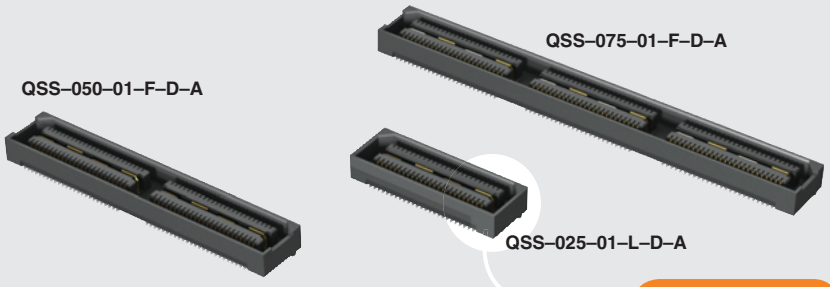
samtec

QSTRIP®



(0,635 mm) .025"

QSS SERIES

HIGH SPEED GROUND PLANE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QSS

Insulator Material: Liquid Crystal Polymer
Contact Material: Phosphor Bronze
Plating: Au or Sn over 50µ" (1,27 µm) Ni
Current Rating: Contact: 1.8 A per pin (1 pin powered per row) Ground Plane: 23.1 A per ground plane (1 ground plane powered)
Operating Temp: -55°C to +125°C
Voltage Rating: 285 VAC
Max Cycles: 100
RoHS Compliant: Yes

Processing:

Lead–Free Solderable: Yes
SMT Lead Coplanarity: (0,10 mm) .004" max (025-050) (0,15 mm) .006" max (075)
Board Stacking: For applications requiring more than two connectors per board contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

ALSO AVAILABLE (MOQ Required)

- 11 mm & 16 mm stack height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)
- 30µ" (0,76 µm) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 100 & 125 positions per row
- Edge Mount
- –LS2 Locking screw hole for QTS–RA–LS2

Contact Samtec.

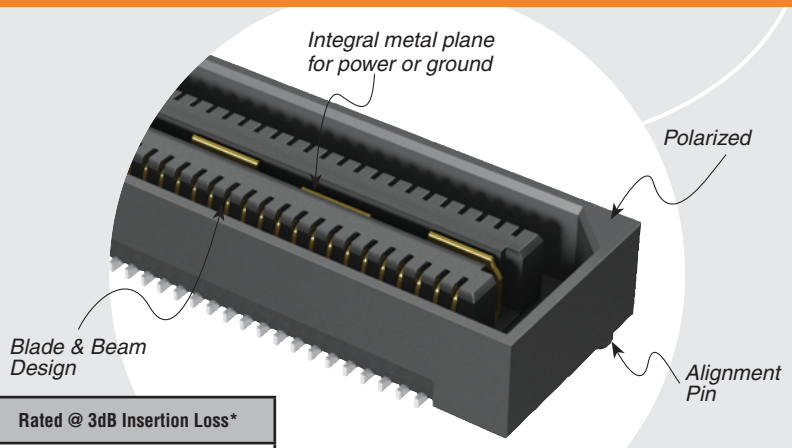
***Note:** –C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.

Board Mates:
QTS

Cable Mates:
SQCD

E.L.P.™
EXTENDED LIFE PRODUCT
10 year Mixed Flowing Gas with 50µ" Gold
Call Samtec for maximum mated cycles



QSS/QTS 5 mm Stack Height	Type	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	–D	9 GHz / 18 Gbps
Differential Pair Signaling	–D	8.5 GHz / 17 Gbps
Differential Pair Signaling	–DP	8.5 GHz / 17 Gbps

*Performance data includes effects of a non-optimized PCB.
Performance data for other stack heights and complete test data available at www.samtec.com?QSS or contact sig@samtec.com

Final Inch® CERTIFIED

QSS	–	NO. OF POSITIONS PER ROW	–	01	–	PLATING OPTION	–	D	–	A	–	OTHER OPTION

–025, –050, –075
(50 total positions per bank)

–F
= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

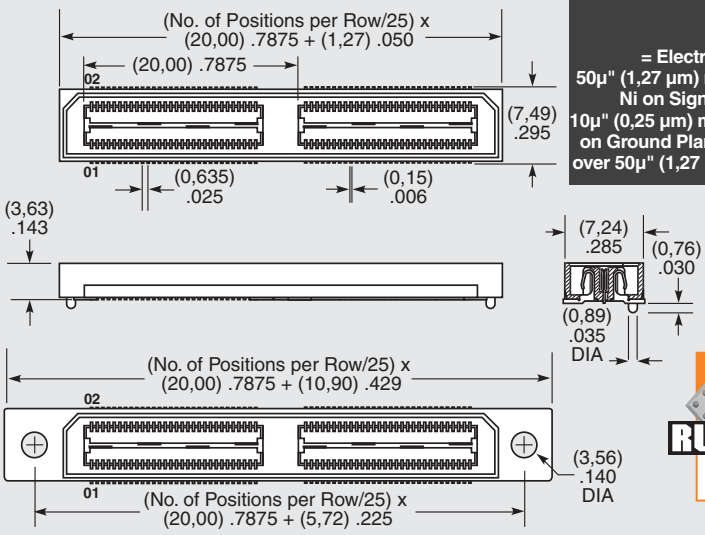
–L
= 10µ" (0,25 µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

–C*
= Electro-Polished Selective 50µ" (1,27 µm) min Au over 150µ" (3,81 µm) Ni on Signal Pins in contact area, 10µ" (0,25 µm) min Au over 50µ" (1,27 µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1,27 µm) min Ni on all solder tails

–GP
= Guide Holes for mating with QTS-RA

–K
= (8,25 mm) .325" DIA Polyimide Film Pick & Place Pad

–TR
= Tape and Reel



OTHER SOLUTIONS

RUGGEDIZED by SAMTEC

- Board spacing standoffs (See SO Series)